DMA2610H

Silicon PNP epitaxial planar type

For digital circuits

Features

- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

Marking Symbol: R4

Basic Part Number

Dual DRA2123Y (Common emitter)

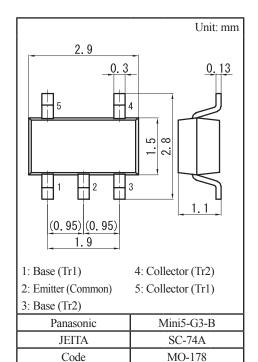
Packaging

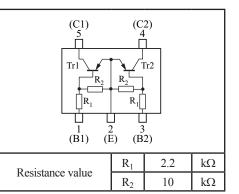
DMA2610H0R Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

Absolute Maximum Ratings $T_a = 25^{\circ}C$

	Parameter	Symbol	Symbol Rating	
Tr1 Tr2	Collector-base voltage (Emitter open)	V _{CBO}	-50	V
	Collector-emitter voltage (Base open)	V _{CEO}	-50	V
	Collector current	I _C	-100	mA
Overall	Total power dissipation	P _T	300	mW
	Junction temperature	Tj	150	°C
	Operating ambient temperature	T _{opr}	-40 to +85	°C
	Storage temperature	T _{stg}	-55 to +150	°C

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

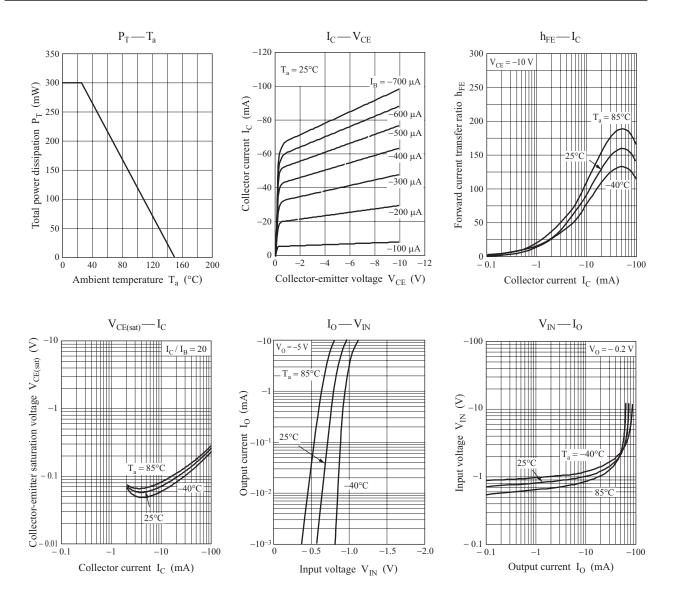




Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = -10 \ \mu {\rm A}, I_{\rm E} = 0$	-50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -2 {\rm mA}, I_{\rm B} = 0$	-50			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{\rm CB} = -50$ V, $I_{\rm E} = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{\rm CE} = -50 \text{ V}, I_{\rm B} = 0$			- 0.5	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = -6 V, I_C = 0$			-1.0	mA
Forward current transfer ratio	h _{FE}	$V_{\rm CE} = -10$ V, $I_{\rm C} = -5$ mA	30			
h _{FE} ratio *1	h _{FE} (Small/Large)	$V_{CE} = -10 \text{ V}, I_C = -5 \text{ mA}$	0.50	0.99		
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -10 \text{ mA}, I_{\rm B} = -0.5 \text{ mA}$			-0.25	V
Input voltage (ON)	V _{I(on)}	$V_{CE} = -0.2 \text{ V}, I_C = -5 \text{ mA}$	-1.1			V
Input voltage (OFF)	V _{I(off)}	$V_{CE} = -5 \text{ V}, I_C = -100 \mu\text{A}$			- 0.5	V
Input resistance	R ₁		-30%	2.2	+30%	kΩ
Resistance ratio	R ₁ / R ₂		0.17	0.22	0.27	

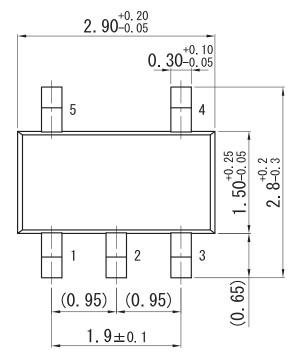
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors. 2. *1: Ratio between 2 elements

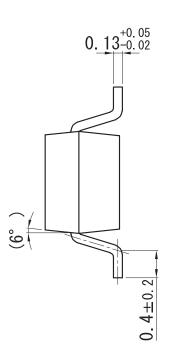
Panasonic

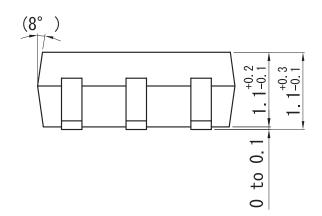


Unit: mm

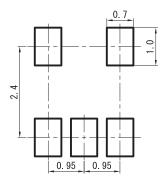
Mini5-G3-B







Land Pattern (Reference) (Unit: mm)



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